### 2.5 V / 3.3 V Differential 2:1 Clock IN to Differential LVPECL Clock Generator / Divider / Fan-Out Buffer

## Multi-Level Inputs w/ Internal Termination

## Description

The NB4L339 is a multi-function Clock generator featuring a 2:1 Clock multiplexer front end and simultaneously outputs a selection of four different divide ratios from its four divider blocks; $\div 1 / \div 2 / \div 4 / \div 8$. One divide block has a choice of $\div 1$ or $\div 2$.

The output of each divider block is fanned-out to two identical differential LVPECL copies of the selected clock. All outputs provide standard LVPECL voltage levels when externally terminated with a $50-$ ohm resistor to $\mathrm{V}_{\mathrm{CC}}-2 \mathrm{~V}$.

The differential Clock inputs incorporate internal $50-\Omega$ termination resistors and will accept LVPECL, CML or LVDS logic levels.

The common Output Enable pin ( $\overline{\mathrm{EN}}$ ) is synchronous so that the internal dividers will only be enabled/disabled when the internal clock is in the LOW state. This avoids any chance of generating a runt clock pulse on the internal clock when the device is enabled/disabled as can happen with an asynchronous control. An internal runt pulse could lead to losing synchronization between the internal divider stages. The internal enable flip-flop is clocked on the falling edge of the input clock. Therefore, all associated specification limits are referenced to the negative edge of the clock input.

This device is housed in a $5 \times 5 \mathrm{~mm} 32$ pin QFN package.

## Features

- Maximum Input/Output Clock Frequency $>700 \mathrm{MHz}$
- Low Skew LVPECL Outputs, 15 ps typical
- 1 ns Typical Propagation Delay
- 150 ps Typical Rise and Fall Times
- 0.15 ps Typical RMS Phase Jitter
- 0.5 ps Typical RMS Random Clock Period Jitter
- LVPECL, CML or LVDS Input Compatible
- Operating Range: $\mathrm{V}_{\mathrm{CC}}=2.375 \mathrm{~V}$ to 3.6 V with $\mathrm{V}_{\mathrm{EE}}=0 \mathrm{~V}$
- LVPECL Output Level; 750 mV Peak-to-Peak, Typical
- Internal 50- $\Omega$ Input Termination Provided
- Synchronous Output Enable/Disable
- Asynchronous Master Reset
- Functionally Compatible with Existing 2.5 V / 3.3 V LVEL, LVEP, EP, and SG Devices
- $-40^{\circ} \mathrm{C}$ to $85^{\circ} \mathrm{C}$ Ambient Operating Temperature
- $32-\mathrm{Pin}$ QFN, $5 \mathrm{~mm} \times 5 \mathrm{~mm}$
- This is a $\mathrm{Pb}-$ Free Device


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A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week

- $\quad=$ Pb-Free Package
(Note: Microdot may be in either location)


Figure 1. Simplified Block Diagram


Figure 2. Detailed Logic Diagram

Table 1. Input Select Function Table

| CLKSEL* | CLK Input Selected |
| :---: | :---: |
| 0 | CLKA |
| 1 | CLKB |

Table 2. Divider Select Function Table

| DIVSEL* | QA Divide |
| :---: | :--- |
| 0 | Divide by 1 |
| 1 | Divide by 2 |

Table 3. Clock Enable/Disable Function Table

| CLK Input | $\mathbf{E N}^{\star}$ | $\mathbf{M R}^{\star \star}$ | Function |
| :---: | :---: | :---: | :---: |
| Low to High Transition | 0 | H | Divide - Outputs Active |
| High to Low Transition | 1 | H | Hold Q - Outputs Inactive |
| X (Don't Care) | X (Don't Care) | L | Reset Q |

* Pin will default LOW when left OPEN. ** Pin will default HIGH when left OPEN.


Figure 3. Pinout QFN-32 (Top View)

Table 4. Pin Description

| Pin | Name | I/O | Description |
| :---: | :---: | :---: | :--- |
| 1,8, EP | V $_{\text {EE }}$ | - | Negative Supply Voltage |
| 2 | CLKA | LVPECL, CML, | Non-inverted differential input (A). (Note 1) |
| 3 | VTA | - | Input |

1. In the differential configuration when the input termination pin ( $\mathrm{VTx} / \overline{\mathrm{VTx}}$ ) are connected to a common termination voltage or left open, and if no signal is applied on CLKx / CLKx input then the device will be susceptible to self-oscillation.

NB4L339

Table 5. ATTRIBUTES

| Characteristics | Value |
| :---: | :---: |
| Input Default State Resistors | $80 \mathrm{k} \Omega$ |
| ESD Protection $\begin{gathered}\text { Human Body Model } \\ \text { Machine Model }\end{gathered}$ | $\begin{aligned} & >2.0 \mathrm{kV} \\ & >100 \mathrm{~V} \end{aligned}$ |
| Moisture Sensitivity (Note 2) QFN-32 | Level 1 |
| Flammability Rating Oxygen Index: 28 to 34 | UL 94 V-0 @ 0.125 in |
| Transistor Count | 366 |
| Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test |  |

2. For additional information, see Application Note AND8003/D.

Table 6. MAXIMUM RATINGS

| Symbol | Parameter | Condition 1 | Condition 2 | Rating | Units |
| :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\mathrm{CC}}$ | Positive Power Supply | $\mathrm{V}_{\text {EE }}=0 \mathrm{~V}$ |  | 4.0 | V |
| $\mathrm{V}_{10}$ | Input/Output Voltage | $\mathrm{V}_{\mathrm{EE}}=0 \mathrm{~V}$ | $-0.5=\mathrm{V}_{10} \leq \mathrm{V}_{\mathrm{CC}}+0.5$ | 4.0 | V |
| $\mathrm{V}_{\text {INPP }}$ | Differential Input Voltage Swing $\quad$ \|CLK - CLK| |  |  | 2.8 | V |
| $\mathrm{I}_{\mathrm{N}}$ | Input Current Through $\mathrm{R}_{\mathrm{T}}(50 \Omega$ Resistor) | Static Surge |  | $\begin{aligned} & 45 \\ & 80 \end{aligned}$ | mA |
| Iout | Output Current | Continuous Surge |  | $\begin{gathered} 50 \\ 100 \end{gathered}$ | mA |
| $\mathrm{T}_{\text {A }}$ | Operating Temperature Range | QFN-32 |  | -40 to +85 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{\text {stg }}$ | Storage Temperature Range |  |  | -65 to +150 | ${ }^{\circ} \mathrm{C}$ |
| $\theta_{\text {JA }}$ | Thermal Resistance (Junction-to-Ambient) (Note 3) | $\begin{aligned} & 0 \text { LFPM } \\ & 500 \text { LFPM } \end{aligned}$ | $\begin{aligned} & \text { QFN-32 } \\ & \text { QFN-32 } \end{aligned}$ | $\begin{aligned} & 31 \\ & 27 \end{aligned}$ | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| $\theta_{\text {Jc }}$ | Thermal Resistance (Junction-to-Case) | (Note 3) | QFN-32 | 12 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| $\mathrm{T}_{\text {sol }}$ | Wave Solder (Pb-Free) |  |  | 265 | ${ }^{\circ} \mathrm{C}$ |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.
3. JEDEC standard multilayer board - 2S2P (2 signal, 2 power) with 8 filled thermal vias under exposed pad.

Table 7. DC CHARACTERISTICS, CLOCK Inputs, LVPECL Outputs
$\mathrm{V}_{\mathrm{CC}}=2.375 \mathrm{~V}$ to $3.6 \mathrm{~V}, \mathrm{~V}_{\mathrm{EE}}=0 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}$ to $+85^{\circ} \mathrm{C}$ (Note 5)

| Symbol | Characteristic | Min | Typ | Max | Unit |
| :--- | :--- | :---: | :---: | :---: | :---: |
| $I_{\text {EE }}$ | Power Supply Current (Inputs and Outputs Open) | 58 | 70 | 90 | mA |

LVPECL Outputs (Note 4)

| $\mathrm{V}_{\mathrm{OH}}$ | Output HIGH Voltage | $\mathrm{V}_{\mathrm{CC}}=3.3 \mathrm{~V}$ | $\mathrm{~V}_{\mathrm{CC}}-1135$ | $\mathrm{~V}_{\mathrm{CC}}-1020$ | $\mathrm{~V}_{\mathrm{CC}}-760$ | mV |
| :--- | :--- | :--- | :---: | :---: | :---: | :---: |
|  |  | $\mathrm{V}_{\mathrm{CC}}=2.5 \mathrm{~V}$ | 1355 | 2280 | 2540 |  |
|  |  |  | 1480 | 1740 |  |  |
| $\mathrm{~V}_{\mathrm{OL}}$ | Output LOW Voltage |  | $\mathrm{V}_{\mathrm{CC}}-1935$ | $\mathrm{~V}_{\mathrm{CC}}-1770$ | $\mathrm{~V}_{\mathrm{CC}}-1560$ | mV |
|  |  | $\mathrm{V}_{\mathrm{CC}}=3.3 \mathrm{~V}$ | 1355 | 1530 | 1740 |  |
|  |  |  | $\mathrm{~V}_{\mathrm{CC}}=2.5 \mathrm{~V}$ | 555 | 730 | 940 |

Differential Input Driven Single-Ended (see Figures 6 \& 8)

| Vth | Input Threshold Reference Voltage Range (Note 6) | 1125 |  | $\mathrm{~V}_{\mathrm{CC}}-75$ | mV |
| :--- | :--- | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\mathrm{IH}}$ | Single-ended Input HIGH Voltage | $\mathrm{Vth}+75$ |  | $\mathrm{~V}_{\mathrm{CC}}$ | mV |
| $\mathrm{V}_{\mathrm{IL}}$ | Single-ended Input LOW Voltage | $\mathrm{V}_{\mathrm{EE}}$ |  | $\mathrm{Vth}^{-75}$ | mV |
| $\mathrm{V}_{\text {ISE }}$ | Single-ended Input Voltage $\left(\mathrm{V}_{\mathrm{IH}}-\mathrm{V}_{\mathrm{IL}}\right)$ | 150 |  | 2800 | mV |

Differential Inputs Driven Differentially (see Figures 7 \& 9)

| $\mathrm{V}_{\text {IHD }}$ | Differential Input HIGH Voltage | 1200 |  | $\mathrm{~V}_{\mathrm{CC}}$ | mV |
| :--- | :--- | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\text {ILD }}$ | Differential Input LOW Voltage | $\mathrm{V}_{\mathrm{EE}}$ |  | $\mathrm{V}_{\mathrm{CC}}-150$ | mV |
| $\mathrm{V}_{\mathrm{CMR}}$ | Input Common Mode Range (Differential Configuration) (Note 8) | 1125 |  | $\mathrm{~V}_{\mathrm{CC}}-75$ | mV |
| $\mathrm{V}_{\text {ID }}$ | Differential Input Voltage Swing (VIHD - $\mathrm{V}_{\text {ILD }}$ |  | 150 |  | 2800 |
| $\mathrm{I}_{\mathrm{IH}}$ | Input HIGH Current $\quad$ CLKx/ CLKx $\quad$ (VTx Open) | mV |  |  |  |
| $\mathrm{I}_{\mathrm{IL}}$ | Input LOW Current $\quad$ CLKx/ CLKx $\quad$ (VTx Open) | -10 | 40 | $\mu \mathrm{~A}$ |  |

## Single-Ended LVCMOS / LVTTL Control Inputs

| $\mathrm{V}_{\mathrm{IH}}$ | Single-ended Input HIGH Voltage |  | 2000 | $\mathrm{V}_{\mathrm{CC}}$ | mV |
| :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\text {IL }}$ | Single-ended Input LOW Voltage |  | $\mathrm{V}_{\mathrm{EE}}$ | 800 | mV |
| $\mathrm{I}_{\mathrm{H}}$ | Input HIGH Current | CLKSEL, DIVSEL, $\frac{\mathrm{EN}}{\mathrm{MR}}$ | $\begin{gathered} 40 \\ -10 \end{gathered}$ | $\begin{gathered} 115 \\ 10 \end{gathered}$ | $\mu \mathrm{A}$ |
| $\mathrm{I}_{\text {LL }}$ | Input LOW Current | CLKSEL, DIVSEL, EN | $\begin{gathered} \hline-10 \\ -115 \end{gathered}$ | $\begin{gathered} 10 \\ -40 \end{gathered}$ | $\mu \mathrm{A}$ |

## Termination Resistors

| $R_{\text {TIN }}$ | Internal Input Termination Resistor (Measured across CLKx and CLKx $)$ | 80 | 100 | 120 | $\Omega$ |
| :--- | :--- | :---: | :---: | :---: | :---: |
| $R_{\text {TIN }}$ | Internal Input Termination Resistor (Measured from CLKx to VTx) | 40 | 50 | 60 | $\Omega$ |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.
4. LVPECL outputs require $50 \Omega$ receiver termination resistors to $\mathrm{V}_{\mathrm{CC}}-2 \mathrm{~V}$ for proper operation.
5. Input and output parameters vary $1: 1$ with $\mathrm{V}_{\mathrm{CC}}$.
6. Vth is applied to the complementary input when operating in single-ended mode.
7. $\mathrm{V}_{I H D}, \mathrm{~V}_{I L D}, \mathrm{~V}_{I D}$ and $\mathrm{V}_{\mathrm{CMR}}$ parameters must be complied with simultaneously.
8. $\mathrm{V}_{\text {CMR }}$ min varies $1: 1$ with $\mathrm{V}_{\mathrm{EE}}, \mathrm{V}_{\mathrm{CMR}}$ max varies $1: 1$ with $\mathrm{V}_{\mathrm{CC}}$. The $\mathrm{V}_{\mathrm{CMR}}$ range is referenced to the most positive side of the differential input signal.

Table 8. AC CHARACTERISTICS $\mathrm{V}_{\mathrm{CC}}=2.375 \mathrm{~V}$ to $3.6 \mathrm{~V}, \mathrm{~V}_{\mathrm{EE}}=0 \mathrm{~V}$ (Note 9)

| Symbol | Characteristic | $-40^{\circ} \mathrm{C}$ |  |  | $25^{\circ} \mathrm{C}$ |  |  | $85^{\circ} \mathrm{C}$ |  |  | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | Min | Typ | Max | Min | Typ | Max | Min | Typ | Max |  |
| $\mathrm{fin}_{\text {max }}$ | Maximum Input CLOCK Frequency | 700 |  |  | 700 |  |  | 700 |  |  | MHz |
| V ${ }_{\text {OUTPP }}$ | Output Voltage Amplitude (@ VINPPmin) <br> (See Figure 4) $\mathrm{f}_{\text {in }}^{\substack{\mathrm{n}}} \leq 622 \mathrm{mHz}$ | 530 | 730 |  | 530 | 730 |  | 530 | 730 |  | mV |
| $\begin{aligned} & \hline \mathrm{tPLH}^{\prime}, \\ & \mathrm{t}_{\mathrm{PHL}} \end{aligned}$ | Propagation Delay to CLKx/CLKx to $\mathrm{Qx} / \mathrm{Qx}$ <br> Output Differential $\div 1$ MR to Qx <br>  CLKSEL to Qx | $\begin{aligned} & 0.8 \\ & 1.2 \\ & 0.8 \end{aligned}$ | $\begin{gathered} 1.0 \\ - \\ 1.0 \end{gathered}$ | $\begin{aligned} & 1.3 \\ & 5.0 \\ & 1.3 \end{aligned}$ | $\begin{aligned} & 0.8 \\ & 1.2 \\ & 0.8 \end{aligned}$ | $\begin{gathered} 1.0 \\ - \\ 1.0 \end{gathered}$ | $\begin{aligned} & 1.3 \\ & 5.0 \\ & 1.3 \end{aligned}$ | $\begin{aligned} & 0.8 \\ & 1.2 \\ & 0.8 \end{aligned}$ | $\begin{gathered} 1.0 \\ - \\ 1.0 \end{gathered}$ | $\begin{aligned} & 1.3 \\ & 5.0 \\ & 1.3 \end{aligned}$ | ns |
| trr | Reset Recovery | 4.0 |  |  | 4.0 |  |  | 4.0 |  |  | ns |
| DCO | Output CLOCK Duty Cycle All Divides | 40 |  | 60 | 40 |  | 60 | 40 |  | 60 | \% |
| tskew | Within Device Skew (Note 11) Device to Device Skew (Note 12) |  | $\begin{aligned} & 30 \\ & 90 \end{aligned}$ | $\begin{gathered} 60 \\ 190 \end{gathered}$ |  | $\begin{aligned} & 30 \\ & 90 \end{aligned}$ | $\begin{gathered} \hline 60 \\ 190 \end{gathered}$ |  | $\begin{aligned} & 30 \\ & 90 \end{aligned}$ | $\begin{gathered} \hline 60 \\ 190 \end{gathered}$ | ps |
| $\mathrm{t}_{\mathrm{s}}$ | Setup Time @ 50 MHz EN to CLKx <br> DIVSEL to CLKx | $\begin{gathered} \hline 900 \\ -100 \end{gathered}$ |  |  | $\begin{gathered} \hline 900 \\ -100 \end{gathered}$ |  |  | $\begin{gathered} \hline 900 \\ -100 \end{gathered}$ |  |  | ps |
| $\mathrm{th}_{\mathrm{h}}$ | Hold Time @ 50 MHzCLKx to EN <br> CLKx to DIVSEL | $\begin{gathered} 800 \\ 0 \end{gathered}$ |  |  | $\begin{gathered} 800 \\ 0 \end{gathered}$ |  |  | $\begin{gathered} 800 \\ 0 \end{gathered}$ |  |  | ps |
| tpw | Minimum Pulse Width $\overline{\mathrm{MR}}$ | 5.0 |  |  | 5.0 |  |  | 5.0 |  |  | ns |
| $\Phi_{N}$ | Phase Noise $\mathrm{f}_{\text {in }}=622.08 \mathrm{MHz}$ <br> Outputs (A) Div by 1  <br> 10 kHz  <br> 100 kHz  <br> 1 MHz  <br> 10 MHz  <br> 20 MHz  <br> 40 MHz  |  |  |  |  | $\begin{aligned} & -136 \\ & -136 \\ & -141 \\ & -141 \\ & -141 \\ & -141 \end{aligned}$ |  |  |  |  | dBc |
| $\mathrm{t}_{\text {IIT1 }}$ | Integrated Phase Jitter (Figure 4) $\mathrm{f}_{\text {in }}=622.08 \mathrm{MHz}, 12 \mathrm{kHz}-20 \mathrm{MHz}$ Offset All Divides |  | 0.15 | 0.25 |  | 0.15 | 0.25 |  | 0.15 | 0.25 | $\begin{gathered} \text { ps } \\ \text { RMS } \end{gathered}$ |
| $\mathrm{t}_{\text {JIT2 }}$ | Random Clock Period Jitter (Note 13) $\mathrm{f}_{\text {in }}=622.08 \mathrm{MHz}$ <br> All Divides |  | 0.5 | 1.5 |  | 0.5 | 1.5 |  | 0.5 | 1.5 | $\begin{gathered} \text { ps } \\ \text { RMS } \end{gathered}$ |
| $\mathrm{V}_{\text {INPP }}$ | Input Voltage Swing/Sensitivity (Differential Configuration) (Note 14) | 150 |  |  | 150 |  |  | 150 |  |  | mV |
| $\mathrm{tr}_{\mathrm{r}}, \mathrm{t}_{\mathrm{f}}$ | Output Rise/Fall Times @ 622.08 MHz input frequency ( $20 \%-80 \%$ ) |  | 150 | 250 |  | 150 | 250 |  | 150 | 250 | ps |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.
9. Measured by forcing $\mathrm{V}_{\text {INPP }}(\mathrm{Min})$ from a $50 \%$ duty cycle clock source. All loading with an external $\mathrm{R}_{\mathrm{L}}=50 \Omega$ to $\mathrm{V}_{\mathrm{CC}}-2 \mathrm{~V}$ Input edge rates 100 ps (20\% - 80\%).
10. Duty cycle skew is measured between differential outputs using the deviations of the sum of Tpw- and Tpw+@ 50 MHz .
11. Skew is measured between outputs under identical transitions and conditions. Duty cycle skew is defined only for differential operation when the delays are measured from the cross-point of the inputs to the cross-point of the outputs.
12. Device to device skew is measured between outputs under identical transition @ 50 MHz .
13. Additive RMS jitter with $50 \%$ duty cycle clock signal; all inputs and outputs active.
14. $\mathrm{V}_{\text {INPP }}$ (Max) cannot exceed $\mathrm{V}_{\mathrm{CC}}-\mathrm{V}_{\mathrm{EE}}$. Input voltage swing is a single-ended measurement operating in differential mode.


Figure 4. NB4L339 vs. Agilent 8665A 622.08 MHz at 3.3 V , Room Ambient


Figure 5. Output Voltage Amplitude ( $\mathrm{V}_{\text {OUTPP }}$ ) vs. Input Clock Frequency ( $\mathrm{f}_{\mathrm{in}}$ ) at Ambient Temperature (Typical)

## Application Information

The NB4L339 is a high-speed, Clock multiplexer, divider and low skew fan-out buffer featuring a $2: 1$ Clock multiplexer front end and outputs a selection of four different divide ratios; $\div 1 / 2 / 4 / 8$. One divide block has a choice of $\div 1$ or $\div 2$. The outputs of all four divider blocks are fanned-out to two pair of identical differential LVPECL copies of the selected clock. All outputs provide standard LVPECL voltage levels when externally terminated with a 50 -ohm resistor to $\mathrm{V}_{\mathrm{TT}}=\mathrm{V}_{\mathrm{CC}}-2 \mathrm{~V}$.

The differential Clock input buffers incorporate internal $50-\Omega$ termination resistors in a $100-\Omega$ center-tapped configuration and are accessible via a VTx pin. This feature provides transmission line termination on-chip, at the receiver end, eliminating external components. Inputs CLKA/B and $\overline{\text { CLKA }} / \overline{\mathrm{B}}$ must be signal driven or auto oscillation may result.

The NB4L339 Clock inputs can be driven by a variety of differential signal level technologies including LVDS, LVPECL, or CML.

The internal dividers are synchronous to each other. Therefore, the common output edges are precisely aligned.

The Output Enable pin ( $\overline{\mathrm{EN}}$ ) is synchronous so that the internal divider flip-flops will only be enabled/disabled when the internal clock is in the LOW state. This avoids any chance of generating a runt pulse on the internal clock when the device is enabled/disabled, as can happen with an asynchronous control. The internal enable flip-flop is clocked on the falling edge of the input clock. Therefore, all associated specification limits are referenced to the negative edge of the clock input.

The Master Reset $(\overline{\mathrm{MR}})$ is asynchronous. When $\overline{\mathrm{MR}}$ is forced LOW, all Q outputs go to logic LOW.


Figure 6. Timing Diagram


NOTE: On the rising edge of $\overline{\mathrm{MR}}, \mathrm{Q}$ goes HIGH after the first rising edge of CLK, following a high-to-low clock transition.
Figure 7. Master Reset Timing Diagram


Figure 8. Output Enable Timing Diagrams

The $\overline{\mathrm{EN}}$ signal will "freeze" the internal divider flip-flops on the first falling edge of CLK after its assertion. The internal divider flip-flops will maintain their state during the freeze. When $\overline{\mathrm{EN}}$ is deasserted (LOW), and after the next
falling edge of CLK, then the internal divider flip-flops will "unfreeze" and continue to their next state count with proper phase relationships.


Figure 9. Input Structure


Figure 11. $\mathrm{V}_{\text {th }}$ Diagram


Figure 13. Differential Inputs Driven Differentially


Figure 10. Differential Input Driven Single-Ended


Figure 12. Differential Inputs Driven Differentially


Figure 14. VCMR Diagram


Figure 15. AC Reference Measurement


Figure 16. LVPECL Interface


Figure 18. Standard $50 \Omega$ Load CML Interface


Figure 20. Capacitor-Coupled Single-Ended Interface ( $\mathrm{V}_{\mathrm{T}}$ Connected to External $\mathrm{V}_{\text {REFAC }}$ )


Figure 17. LVDS Interface


Figure 19. Capacitor-Coupled Differential Interface ( $\mathbf{V}_{\mathbf{T}}$ Connected to External $\mathrm{V}_{\mathrm{REFAC}}$ )
$* V_{\text {REFAC }}$ bypassed to ground with a $0.01 \mu \mathrm{~F}$ capacitor.


Figure 21. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D - Termination of ECL Logic Devices)

## ORDERING INFORMATION

| Device | Package | Shipping $^{\dagger}$ |
| :--- | :---: | :---: |
| NB4L339MNG | QFN32 <br> $(P b-f r e e)$ | 74 Units / Tray |
| NB4L339MNR4G | QFN32 <br> (Pb-free) | $1000 /$ Tape \& Reel |

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D

## NB4L339

## PACKAGE DIMENSIONS

QFN32 5x5, 0.5 P
CASE 488AM
ISSUE O


C


BOTTOM VIEW

NOTES:

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO PLATED

TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM TERMINAL
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

|  | MILLIMETERS |  |  |
| :---: | :---: | :---: | :---: |
| DIM | MIN | NOM | MAX |
| A | 0.800 | 0.900 | 1.000 |
| A1 | 0.000 | 0.025 | 0.050 |
| A3 | 0.200 REF |  |  |
| b | 0.180 | 0.250 | 0.300 |
| D | 5.00 BSC |  |  |
| D2 | 2.950 | 3.100 | 3.250 |
| E | 5.00 BSC |  |  |
| E2 | 2.950 | 3.100 | 3.250 |
| e | 0.500 BSC |  |  |
| K | 0.200 | $-1-$ | --- |
| L | 0.300 | 0.400 | 0.500 |

SOLDERING FOOTPRINT*

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